

Customer No.: 31561
Application No.: 10/707,825
Docket NO.: 10786-US-PA

AMENDMENT

Please amend the application as indicated hereafter.

In the Claims :

1. (original) A flip-chip gold bump structure formed on a wafer, comprising:
 - at least one gold bump;
 - a nickel layer on the gold bump; and
 - a copper layer on the nickel layer.
2. (original) The flip-chip gold bump structure of claim 1, wherein the nickel layer has a thickness about from 0.1 μm to about 20 μm .
3. (original) The flip-chip gold bump structure of claim 1, wherein the copper layer has a thickness about from 0.1 μm to about 10 μm .
4. (original) The flip-chip gold bump structure of claim 1, wherein the gold bump has a height about from 3 μm to about 150 μm .
5. (original) A flip-chip package structure adapted to connect a chip and a chip substrate, comprising:
 - at least one gold bump on the chip;

Customer No.: 31561
Application No.: 10/707,825
Docket NO.: 10786-US-PA

a nickel layer on the gold bump; and
a solder containing copper on the nickel layer for connecting the chip and the chip substrate.

6. (original) The flip-chip package structure of claim 5, wherein the solder containing copper includes a solder alloy.

7. (original) The flip-chip package structure of claim 6, wherein copper in the solder alloy is from about 0.7 wt.% to about 3.0 wt.%.

8. (original) The flip-chip package structure of claim 5, wherein the nickel layer has a thickness about from 0.1 μ m to about 20 μ m.

9. (original) The flip-chip package structure of claim 5, wherein the gold bump has a height about from 3 μ m to about 150 μ m.

Claims 10-22 (canceled).